

Ethernet For AI: Progress and Challenges

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CTO

LIASON INFORMATION



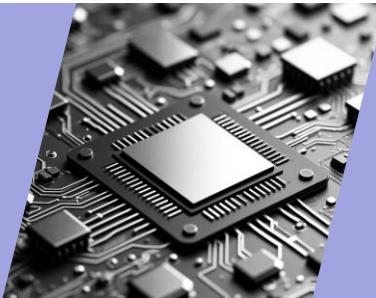
OPEN
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Impacting Data Center IT and Facilities

From hyperscale to distributed edge data center technologies



From silicon to systems to physical facilities



OCP: A Collaborative Community Effort

INCUBATOR

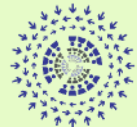
COMMUNITY PROJECTS

NEW INITIATIVES

EMERGING MARKETS



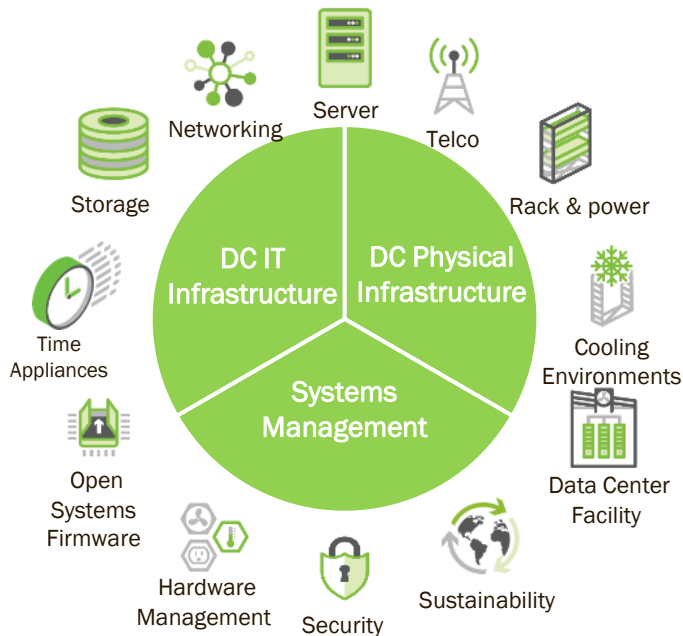
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TECHNOLOGY



Open Systems
for AI



Evenstar
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Test &
Validation

MARKETS



Photonics



Chiplets

OCP MARKETPLACE



Marketplace

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EXPLORE OUR MARKETPLACE SEGMENTS



RECOGNITION PROGRAMS

Security I Facilities



OCP
S.A.F.E.



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READY™

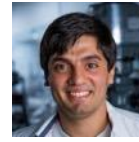
Product



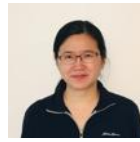
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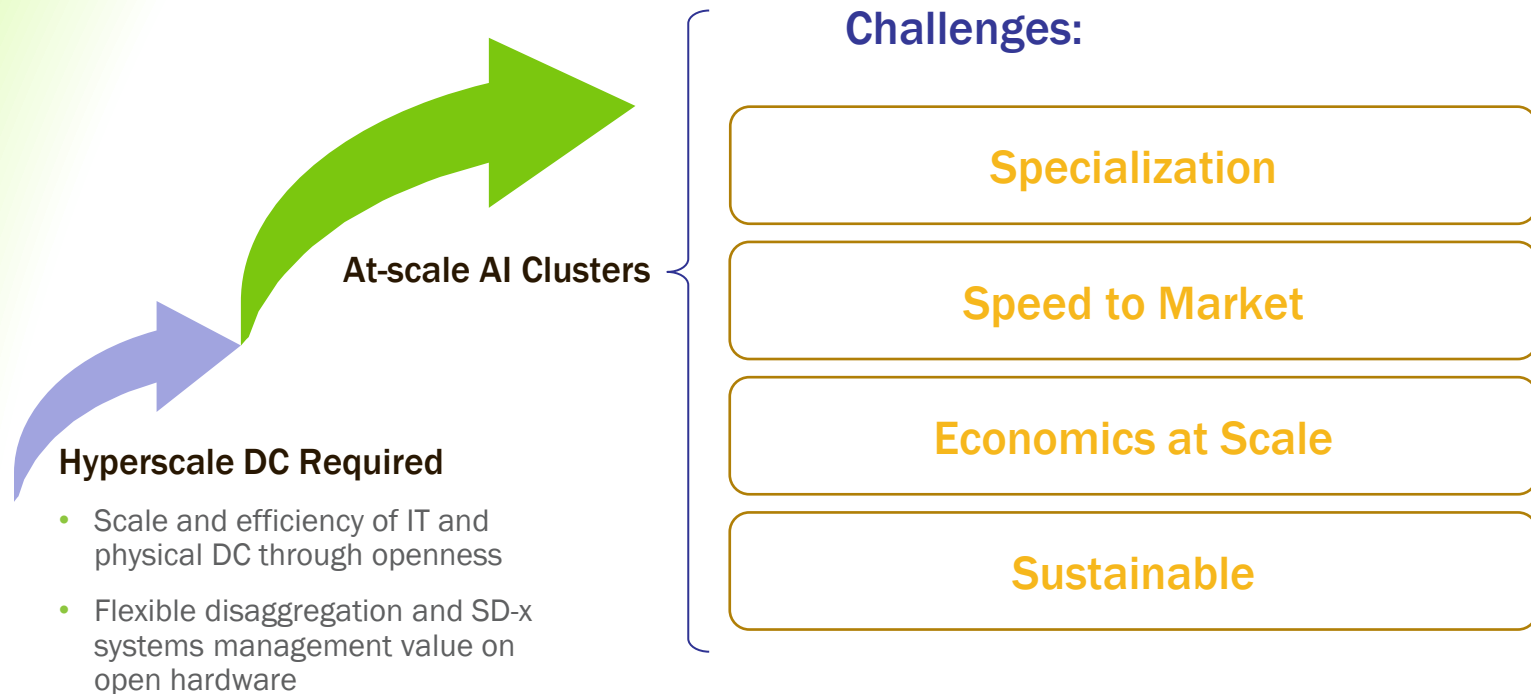
OCP
INSPIRED™



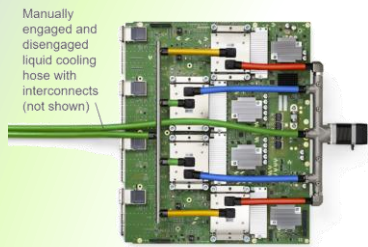
250+ Project Leaders
7,000+ Participants



Tackling the Next DC Technology Shift



OCP Community: AI Progress



Manually engaged and disengaged liquid cooling hose with interconnects (not shown)

(a) Google TPU (ML) version 4 (2021)
Liquid cooled Google server



Blind mate liquid cooling interconnects

(b) Nvidia GB200 NVL72
Liquid Cooled Blind

Announcing GB200 NVL72 Design Contributions to OCP

Accelerating open innovation of AI data centers

Key Contributions		
NVLINK Cable Cartridge 3,000 NVLINK lanes	Enhanced Bus Bar 1,400-amp capacity	Blind Mate Side Rails 100% support
Floating Blind Mate Mechanic linkage	Blind Mate Side Rails NVLINK and LC connections	Latch Bar Support
Rack Reinforcements +100% of steel support	Rear Rack Extenders Protects overhead fittings	Large Cable Cartridge 100% support
Compute Tray Form Factor fits 10U form factor	Compute Tray DC-DCM fits 10U form factor	Compute Tray Highly configurable
Switch Tray Form Factor fits 2U 300-Module Lanes	Switch Tray Bus Bar Connector New power system width	Liquid Flow 3.5x faster

Catalina

ORV3 High Power Rack

- Liquid Cooled FLC Compatible
- Retool Orv3 For Higher Power
- Wedge400 Fabric Switch
- Rack Management
- Modular Design

- Compute (FP8) 2.7x
- HBM Capacity +2x
- HBM BW 2.5x
- Scale Up BW 2x
- Scale Out BW 2x
- Power Density 3-4x

EXPLORE OUR MARKETPLACE SEGMENTS



INFO, SI, OPEN SYSTEMS FOR AI: BLUEPRINT FOR SCALABLE INFRASTRUCTURE

OPEN SYSTEMS FOR AI: BLUEPRINT FOR SCALABLE INFRASTRUCTURE

Contributor: Open Compute Project, Google, Intel, NVIDIA, Denvr Dataworks, Meta, Supermicro, AMD, Dell Technologies

Family: Information

Project: Strategic Initiatives > Open Systems for AI

Release Year: 2025



OCP Community is several generations into building AI technology and systems and now is collaboratively working towards OCP Open Systems for AI

Why are we here today?

OCP Community progress and experience building AI Systems has yielded data and feedback from subject matter experts. The feedback to this point has pointed us to common problem areas.

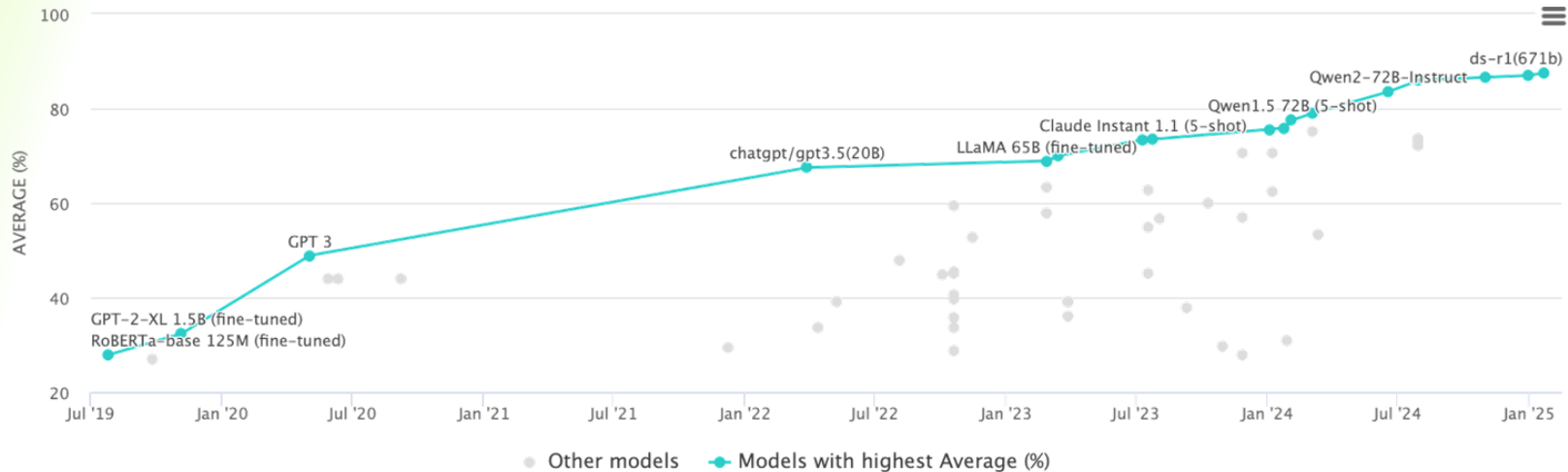
Key feedback points so far:

- Performance is a bottle neck to realizing end user demand
- Technical roadmap/path forward unclear in several important areas
- Risk rising as scale and demand increases
- Economics are not optimal

Early Data Points

- End users: must continue to increase AI intelligence and availability
- Vendors: Increase AI cluster throughput to drive lower unit costs

Multi-task Language Understanding on MMLU



Steady Improvement in intelligence!

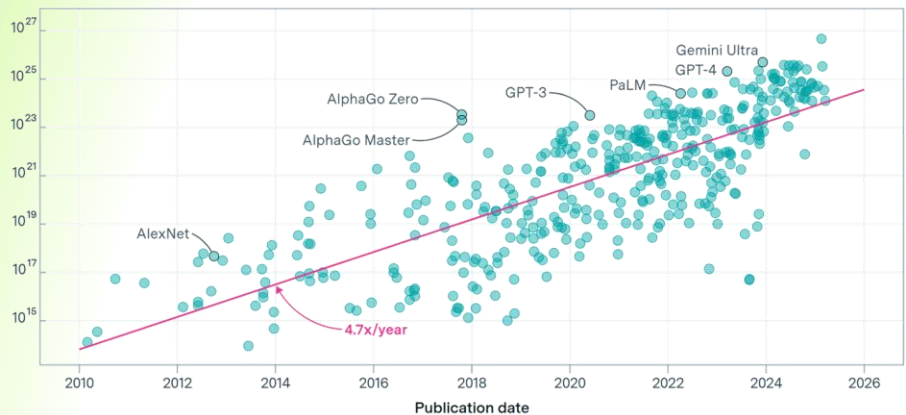
Gen AI LLM (Model) Resource Trends

Training compute of notable models

EPOCH AI

Training compute (FLOP)

407 models

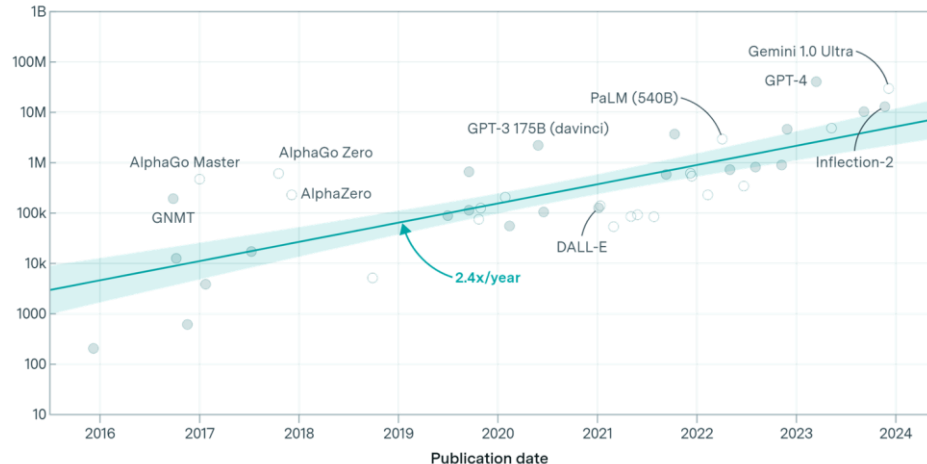


Amortized hardware and energy cost to train frontier AI models over time

EPOCH AI

Cost (2023 USD, log scale)

— Regression mean 90% CI of mean ○ Using estimated cost of TPU



Compute requirements rising at 4.7x/yr and Costs by 2.4x/year

Extrapolating AI Training Cluster Demands

Largest AI Clusters

Year	OOMs	# of H100s-equivalent	Cost	Power	Power reference class
2022	~GPT-4 cluster	~10k	~\$500M	~10 MW	~10,000 average homes
~2024	+1 OOM	~100k	\$billions	~100MW	~100,000 homes
~2026	+2 OOMs	~1M	\$10s of billions	~1 GW	The Hoover Dam, or a large nuclear reactor
~2028	+3 OOMs	~10M	\$100s of billions	~10 GW	A small/medium US state
~2030	+4 OOMs	~100M	\$1T+	~100GW	>20% of US electricity production

OOM = order of magnitude, 10x = 1 order of magnitude. Roughly **~0.5 OOMs/year** trend growth of AI training compute



Scaling the largest training clusters, rough back-of-the-envelope calculations.

Scale everything!

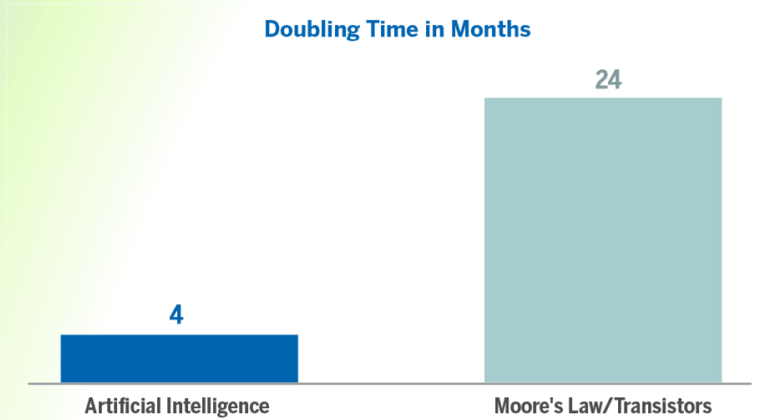
Seeking OOMs Increase in Compute

Non exhaustive, focusing on Existing ISAs:

- **More pipeline throughput** add logic/data path width via increasing transistor count (Moore)
- **Speed Up** increase the clock speeds of the ICs. (assuming caches are optimized).
- **Parallelism** distribute compute in various ways.

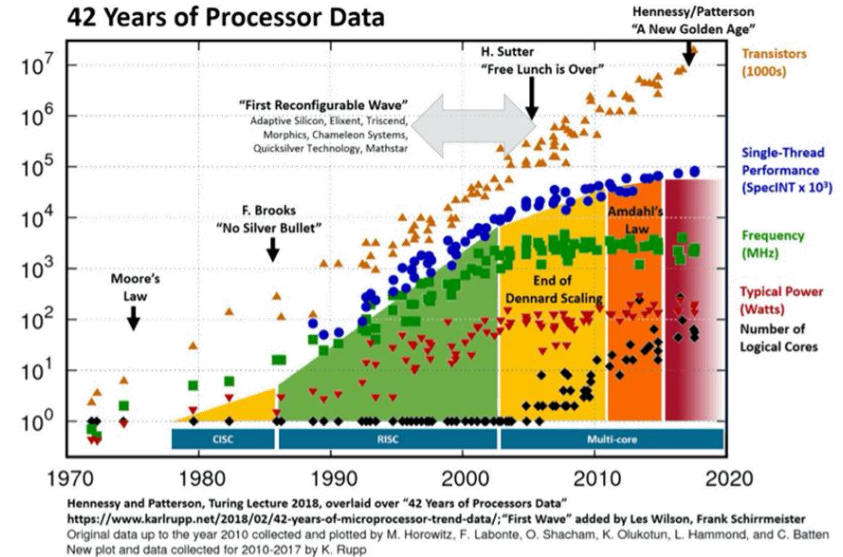
Note other approaches such as addressing the memory wall (ex: CXL) are valid in improving performance but don't accelerate compute by an OOM.

Improve with Processor/IC Scaling?



Source: Intel, Our World in Data, Alger. Moore's Law refers to length of time that it takes for number of transistors per integrated circuit to double. Doubling time for AI refers to the length of time it takes to double the amount of compute or "training" utilized by AI programs. The calculation period used for AI training was 2012 - 2020.

Moore's Law: compute doubles for constant cost roughly once every two years. Quantum effects are beginning to interfere in electronic devices as they shrink.



Dennard Scaling: "Power Wall" has limited practical processor frequency to around 4 -6 GHz since 2006.

IC process scaling for logic is not going to help much. Effective gain (step function) has been realized by adoption of HBM this is data path acceleration.



AI Scaling With Networking?

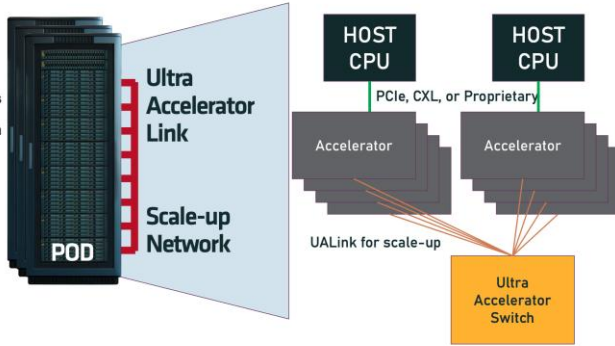


Parallelism with processor-to-processor links and the use of collectives provided a large gain. IEEE 802.3dj speeds (200Gb/s lane) FTW to unleash AI cluster performance.

AI Scaling With Ethernet Fabrics

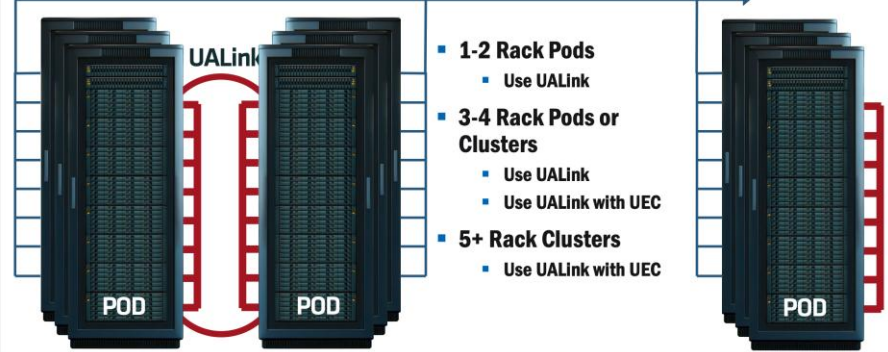
UALink Creates the Scale-Up Pod

- Low latency stack
 - Protocol, Transaction, Link & Physical
- Lower power
 - The simplified UALink stack leads to lower power than Ethernet switching for the same bandwidth
- Lower latency switch
 - Est. Latency: <200ns pin-to-pin
- Lower die area
 - Optimizing the Data Layer and Transaction Layer saves significant die area and reduces cost and TCO



Multiple UALink Pods Can Be Connected With UEC

UEC Scale-out Network



- 1-2 Rack Pods
 - Use UALink
- 3-4 Rack Pods or Clusters
 - Use UALink
 - Use UALink with UEC
- 5+ Rack Clusters
 - Use UALink with UEC



2024

FROM IDEAS TO IMPACT



2024

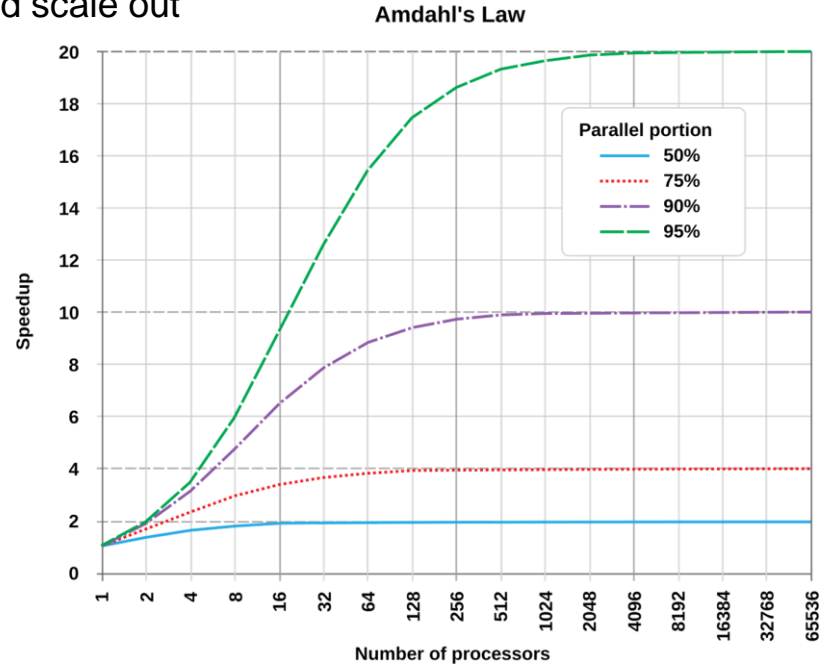
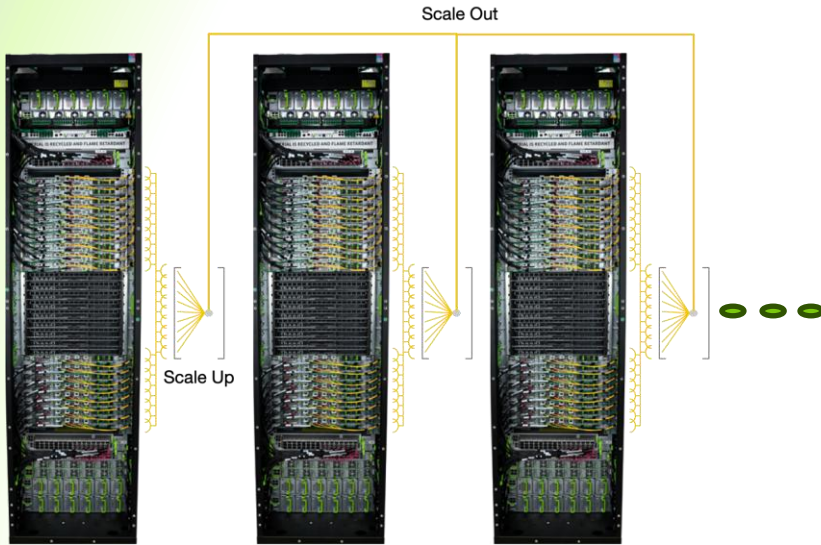
FROM IDEAS TO IMPACT

Scaling up via short reach networking to create an Ethernet fabric to interconnect multiple processors on a system tray, and multiple trays in a rack for a single 'node' or 'pod' via Ethernet switching. Scaling out is a function of meshing the node/pod switches for a cluster.



Networking for the next OOM Improvement

Problem 1: We are physically limited in scale up and scale out



Amdahl's Law shows 1024-2048 nodes max. Economically, deploying 2048 racks doesn't reduce costs and might require 100% utilization for adequate ROI on resources.



Achieving OOM Improvement: 802.3dj

Where do we stand?

Advantages of scaling with 802.3dj

- Double throughput results in far greater xPU performance over 100Gb/s /lane
- Usable Cu cable lengths for AI Clusters
- Multilane to 1.6Tb/s
- Connectors not hard
- Coming soon!

Scaling Challenges

- Increasing to multilane is expensive Radix hit, power wise and thermally
- Max throughput (1.6Tb/s) doesn't match HBM rates (~*8Tb/s HBM3e)
- More lanes = more complexity to maintain

Moving to 200Gb/s is great step forward utilizing Ethernet in AI Clusters. Although this is entering the market in 2H 2025, AI performance demands more throughput to reduce bottlenecks.

Achieving OOM Improvement: 802.3 {NG}

What do we need?

++OOM Ethernet Fabric for Scaling

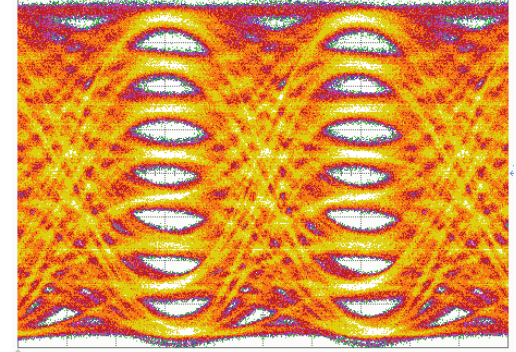
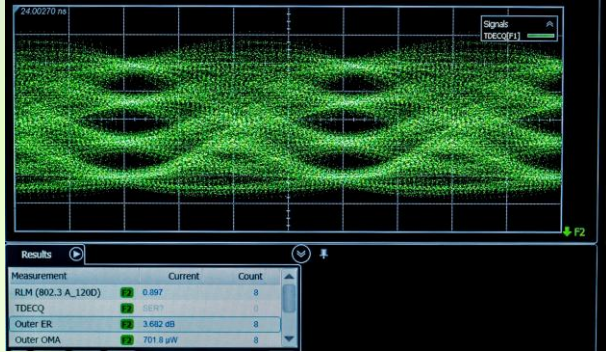
- *Minimum* 2X throughput from 802.3dj
- Cu not a hard requirement. Nice if reach from server tray to tray.
- Capability to reach multilane to 3.2Tb/s (eventually)
- TBD reasonably thermally performant/reliability connectors
- 18-24 months?

Scaling Challenges

- Faster modulation = greater complexity (FEC, etc...)
- Realistically requires faster SERDES (min 224Gb/s)
- Max throughput (3.2Tb/s) doesn't match HBM rates (~*16Tb/s HBM4)
- Uncertainty (Ex is 2X enough?)

Moving to 400Gb/s is great step forward utilizing Ethernet in AI Clusters. The power reduction will be helpful to 2025 workloads, however as scale increases, other/further optimizations may be highly desirable.

Next Steps



Development of use cases and Outreach

- Increase awareness, communicate the vision and identify users and use cases
- We are presently workshopping design for OCP Open Systems for AI. Additional details will help drive clarity on requirements
- Capture requirements from communities and build consensus
- Communicate and meet often!

Thank You